

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
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EPAS ID: PAT4561098

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JASPREET S. GANDHI	01/27/2014
MICHEL KOOPMANS	01/30/2014
<b>RECEIVING PARTY DATA</b>	
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<b>Internal Address:</b>	P.O. BOX 6
<b>City:</b>	BOISE
<b>State/Country:</b>	IDAHO
<b>Postal Code:</b>	83707-0006
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15683336
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	010829-9102.US01
<b>NAME OF SUBMITTER:</b>	SAM BEARD
<b>SIGNATURE:</b>	/Sam Beard/
<b>DATE SIGNED:</b>	08/22/2017
<b>Total Attachments: 4</b>	
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## ASSIGNMENT BY INVENTORS

This Assignment is by the following individuals (the "Assignors"):

- Jaspreet S. Gandhi, having a mailing address of 1145 E. Rubicon Drive, Boise, Idaho 83716; and
- Michel Koopmans, having a mailing address of 2571 S. Waterbury Lane, Boise Idaho 83706.

The Assignors invented one or more certain inventions (the "Invention(s)") described in an application for Letters Patent of the United States titled THERMAL PADS BETWEEN STACKED SEMICONDUCTOR DIES AND ASSOCIATED SYSTEMS AND METHODS, naming the Assignors as inventors, and filed on \_\_\_\_\_ as U.S. Application No. \_\_\_\_\_ (the "Application"). The Assignors authorize the Assignee, identified below, or its representatives to insert the application number and filing date of the Application when known.

Micron Technology, Inc., a corporation of Delaware having its principal place of business at 8000 S. Federal Way, P.O. Box 6, Boise, Idaho 83707-0006 ("Assignee"), desires to acquire the entire right, title and interest in and to the Invention(s) and the Application, and in and to any patents (collectively, "Patents") that may be granted for the Invention(s) in the United States or in any foreign countries.

For valuable consideration, the receipt and sufficiency of which Assignors acknowledge, Assignors hereby sell, assign, and transfer to Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to: the Invention(s), the Application, and any Patents; any divisions, continuations, and continuations-in-part of the Application and any other application claiming priority rights from the Application; any reissues, reexaminations, or extensions of any and all Patents; the right to file foreign applications directly in the name of Assignee; and the right to claim priority rights deriving from the Application (collectively, the "Rights"). Assignors warrant that Assignors own the Rights, and that the Rights are unencumbered. Assignors also agree to not sign any writing or do any act conflicting with this assignment, and, without further compensation, sign all documents and do

such additional acts as Assignee deems necessary or desirable to: perfect Assignee's enjoyment of the Rights; conduct proceedings regarding the Rights, including any litigation or interference proceedings; or perfect or defend title to the Rights. Assignors request the Commissioner of Patents to issue any Patent of the United States that may be issued on the Invention(s) to Assignee. This Assignment may be executed in counterparts.

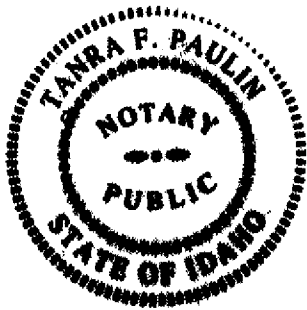
Date: 1/27/2014

Jaspreet S. Gandhi  
Jaspreet S. Gandhi

United States of America )  
State of Idaho ) ss.:  
County of Ada )

On this 27th day of January, 2014, before me personally came Jaspreet S. Gandhi, to me known to be the individual described in and who executed the foregoing instrument, and acknowledged execution of the same.

T. F. Paulin  
Notary Public

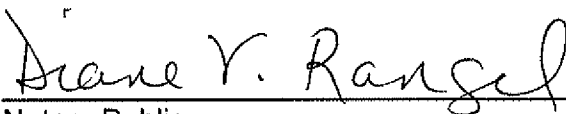


Date: 1/30/2014

  
\_\_\_\_\_  
Michel Koopmans

United States of America )  
State of Idaho ) ss.:  
County of ada )

On this 30<sup>th</sup> day of January, 2014, before me personally came Michel Koopmans, to me known to be the individual described in and who executed the foregoing instrument, and acknowledged execution of the same.

  
\_\_\_\_\_  
Notary Public

